



SCHROFF

24830-005 INTERSCALE FLEXIBLE HEAT CONDUCTOR (FHC), 20 MM



KEY FEATURES

Designed for Intel, AMD, Via, Freescale, NVidia and Texas Instrument processors that employ a BGA socket

Provides industry-leading conduction cooling performance, 10% improvement over current conduction cooling methods

Patent pending conduction cooling solution for small form factor electronics

Secured to PCB with thermally conductive adhesive tape

Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad

Compatible with Interscale C enclosures

PRODUCT ATTRIBUTES

Product Type: Conductor Block

Product Family: Interscale

Type: Heat Conductor

Works With: Cases

Package Quantity: 1

Depth: 22 mm

Width: 22 mm

ADDITIONAL PRODUCT DETAILS

Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad.

CERTIFICATIONS



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